IMPACT
International Microsystems, Packaging, Assembly and Circuits Technology conference

EMAP 2020
The 22nd International Conference on Electronics Materials and Packaging

www.impact.org.tw

IMPACT-EMAP 2020

Oct. 21-23 Taipei, Taiwan

High Performance Computing

Accepted Papers Will Be Collected in IEEE Xplore !

IEEE | IEEE ELECTRONICS PACKAGING SOCIETY | iMAPS Taiwan 台灣國際微電子暨構裝學會 | ITRI Industrial Technology Research Institute | TPCA 台灣電路板協會 Taiwan Printed Circuit Association

Call for Papers

IMPACT-EMAP 2020 Conference, organized by IEEE-EPS-Taipei, iMAPS-Taiwan, ITRI and TPCA, is the largest gathering of PCB and packaging professionals in Taiwan. This year will be held on Oct. 21st -23rd at Taipei Nangang Exhibition Center. For grasping the latest trend, the symposium this year highlights the theme "IMPACT-EMAP on HPC - Toward the Data Era". In the big data era, the fifth-generation (5G) mobile communication network brings out innovative technologies like mmWave and MIMO, which will change everything we know in cellular systems. Driven by high-frequency and high-speed transmission, the demand for processing huge amounts of information has emerged. Big data processing and high-speed computing have become key requirements for the development of the new generation.

IMPACT-EMAP 2020 looks at the cutting-edge technological applications. With the increasing numbers of artificial intelligence (AI) and high-performance data analytics (HPDA), there is a need to expand high-performance computing infrastructure to cope with the challenges of machine learning, deep learning and enable to gain better understanding of digital data. That makes the HPC infrastructure more indispensable than ever.

IMPACT-EMAP 2020 will arrange plenary speeches, special sessions, industrial sessions, invited talks, and outstanding paper and poster presentations. Meanwhile, this conference will keep collaborating with international organizations such as ICEP, JIEP from Japan, KAIST from South Korea, and iNEMI from USA in this year's gathering.

【Date】: Oct 21 (Wed)-23(Fri), 2020

【Venue】: Taipei Nangang Exhibition Center

【Theme】: IMPACT-EMAP on HPC - Toward the Data Era

【On-line Submission】: www.impact.org.tw

【Exhibition】: TPCA Show、TAITRONICS
Laser & Photonics Taiwan
OPTO TAIWAN
AIoT Taiwan、IPC Pavilion

IMPORTANT DATE

Item	Date	Remark
Abstract Submission Deadline (Camera-ready Version)	June 15	400-500 words Submit on-line www.impact.org.tw
Abstract Acceptance Notification	July 15	Notice sent via email
Advance Program Online	August 14	Advanced program announcement
Full Paper Submission (Camera-ready Version)	August 28	4 pages including figures and tables. Submitting on-line through conference website and IEEE copyright forms due

SCOPE OF PAPER SOLICITED

Packaging

P1. Advanced Packaging Technologies

P2. Power Electronics Packaging

P3. Heterogeneous Integration

P4. Wearable Technologies

P5. Interconnections & Nanotechnology

P6. Design, Modeling & Testing

P7. Thermal Management

P8. Advanced Sensor &Microsystems Technology (MST)

P9. Advanced Materials, Automatic Process & Assembly

P10. Emerging Systems Packaging Technologies

PCB

B1. Advanced and Green Materials and Process

B2. Test, Quality, AOI, Inspection and Reliability

B3. HDI Technology(Fine and ultra fine line technology for Rigid、Flex、Rigid/Flex and IC substrate)

B4. Electro Deposition and Electrochemical Processing Technology

B5. Smart Manufacturing and Automation

IMPACT Website

* Papers relevant with the above scopes are encouraged to submit but NOT limited to.
* Conference authority keeps the right to finalize session arrangement.
* Authors of accepted papers including oral presentation and posters should register before the deadline; please be noted that un-registered (paid) papers will be removed from the symposium program.
* The secretariat reserves the right to modify the agenda.

PAPER AWARD

Outstanding Paper Award will be elected by IMPACT-EMAP Technical Program Committee from student and industrial papers respectively. The paper awardees will be announced and honored next year.

SPONSOR

IMPACT-EMAP 2020 sponsors can improve the corporate image, enhance professional development, create networking opportunities and enjoy exclusive benefits. There are multiple sponsorship packages for you to choose!

CONTACT WINDOW

IMPACT-EMAP 2020 Secretariat:
Taiwan Printed Circuit Association (TPCA)
Tel: +886-3-3815659 #407 Cindy #404 Sophia #405 Chelsea
Fax: +886-3-3815150
Email: service@impact.org.tw
http:// www.impact.org.tw

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